IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1					Form Type *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfc Information				
upplier Inform	ation								,						
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
nsemi											2024-05-10				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
uthorized Represe	ntative*		Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
Requeste	er Item Number	Mfr Item Number Mfr Item Name 6N136TSVM 8PW 1MB TR W.		Mfr Item Name			Effective Date	Version	ion Manufacturing Site		V	Veight*	UOM	Unit Type	
				8PW 1MB TR WL	SMD VDE		2024-05-10 THH		НН	473.871		mg	Each		
	Process Information		arminal Paga	Alloy	STD-020 MSL	Poting	Dook Prog	no Pody T	amparatur	May Time at Peak	Tamparati	ura Numb	er of Reflow Cyc	das	
			Terminal Base Alloy J-STD CU Alloy 1		31D-020 MSL	Katilig	Peak Process Body Tempera 260 C		T *				el of Kellow Cyc	les	
•	n (Sn) - annealed	C	U Alluy	1			1200		IC	30	secono	18 3			
omments	ime at peak temperature	during cal	doring is 10.3	0 seconds											
r more informatio	on regarding material co	mposition p	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	nt Unit of Measure Level Substance		Substance	CAS	Exempt	Weight	Unit of Measure	
Coupling Gel	4.37	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.437	mg	
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		3.933	mg	
Die	3.753	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.263	mg	
			Supplier	Silicon (Si)	7440-21-3		3.49	mg	
Die Attach	0.423	mg	Supplier	Silver (Ag)	7440-22-4		0.3173	mg	
			Supplier	Phenolic Resin-2	54208-63-8		0.1058	mg	
Lead Frame	117.616	mg	Supplier	Silver (Ag)	7440-22-4		0.74	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.141	mg	
			Supplier	Iron (Fe)	7439-89-6		2.7	mg	
			Supplier	Copper (Cu)	7440-50-8		114	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.035	mg	
Mold Compound-Black	343.7	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		13.7	mg	
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		68.7001	mg	
			В	Antimony Trioxide (Sb2O3)	1309-64-4		10.3	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		250.9999	mg	
Plating	3.81	mg	Supplier	Tin (Sn)	7440-31-5		3.81	mg	
Wire Bond - Au	0.199	mg	Supplier	Gold (Au)	7440-57-5		0.199	mg	